1

Absolute maximum ratings

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage (I _E = 0)	-60	V
V _{CEO}	Collector-emitter voltage ($I_B = 0$)	-30	V
V _{EBO}	Collector-base voltage $(I_{C} = 0)$	-5	V
Ι _C	Collector current	-3	А
I _{CM}	Collector peak current (t _P < 5ms)	-6	А
I _B	Base current	-1	А
I _{BM}	Base peak current (t _P < 5ms)	-2	А
P _{TOT}	Total dissipation at $T_c = 25^{\circ}C$	12.5	W
T _{STG}	Storage temperature	-65 to 150	°C
TJ	Max. operating junction temperature	150	°C

Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{thJ-case}	Thermal resistance junction-case max	10	°C/W



2 Electrical characteristics

($T_{CASE} = 25^{\circ}C$; unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{CES}	Collector cut-off current (V _{BE} = 0)	V _{CE} = -60 V			-10	μA
I _{CEO}	Collector cut-off current $(I_B = 0)$	V _{CE} = -30 V			-100	μA
I _{EBO}	Emitter cut-off current (I _C = 0)	V _{EB} = -5 V			-10	μA
V _{(BR)CEO}	Collector-emitter breakdown voltage $(I_B = 0)$	I _C = -10 mA	-30			v
V _{(BR)CBO}	Collector-base breakdown voltage $(I_E = 0)$	I _C = -100 μA	-60			v
V _{(BR)EBO}	Emitter-base breakdown voltage $(I_C = 0)$	I _E = -100 μΑ	-5			v
V _{CE(sat)} (1)	Collector-emitter saturation voltage	$ \begin{array}{ll} I_{\rm C} = -1 \ {\rm A} & & I_{\rm B} = -50 \ {\rm mA} \\ I_{\rm C} = -2 \ {\rm A} & & I_{\rm B} = -100 \ {\rm mA} \\ I_{\rm C} = -3 \ {\rm A} & & I_{\rm B} = -150 \ {\rm mA} \end{array} $			-0.4 -0.7 -1.1	< <
V _{BE(sat)} (1)	Base-emitter saturation voltage	I _C = -2 A I _B = -100 mA			-1.2	v
h _{FE}	DC current gain				300	
f _T	Transition frequency	$I_{\rm C} = -0.1$ $V_{\rm CE} = -10$ V		100		MHz

Table 4. Electrical characteristics

1. Pulsed duration = 300 ms, duty cycle $\leq 1.5\%$.



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2.1 Typical characteristics (curves)

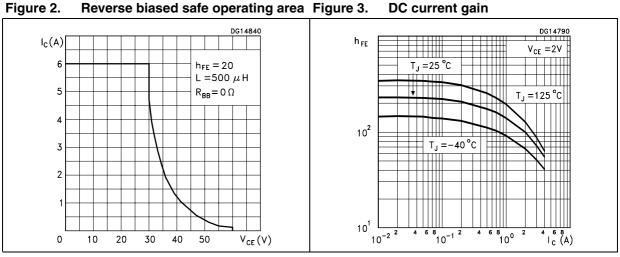
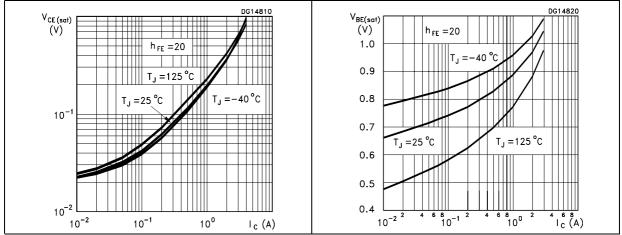


Figure 4. Collector-emitter saturation voltage Figure 5. Base-emitter





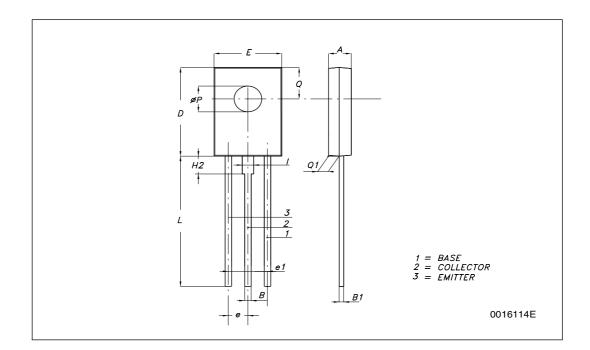
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3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



	SOT-32 (TO-126) mechanical data				
DIM.	mm.				
Dini.	MIN.	ТҮР	MAX.		
Α	2.4		2.9		
В	0.64		0.88		
B1	0.39		0.63		
D	10.5		11.05		
E	7.4		7.8		
е	2.04	2.29	2.54		
e1	4.07	4.58	5.08		
L	15.3		16		
Р	2.9		32		
Q	8				
Q1	1		1.52		
H2		2.15			
I	2				





4 Revision History

Table 5.Document revision history

Date	Revision	Changes
09-Sep-2005	2	Final version. New template
02-Oct-2007	3	Updated mechanical data



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